



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



4

3

2

1

THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION

20

LOC DIST

REVISIONS

© COPYRIGHT 20

BY TYCO ELECTRONICS CORPORATION. ALL INTERNATIONAL RIGHTS RESERVED.

J

-

P LTR

DESCRIPTION

DATE

DWN

APVD

A

RELEASED

13JAN2010

Y.K

Y.N

AS SHOWN : - 1

Ø0.7 REF
(PICK UP AREA)

2.4 REF

0.93

1.7

0.4

0.18 REF
(WIPING AMOUNT)

0.95
(PCB HEIGHT)

1.05

0.45

2

0.42 REF
(CONTACT AREA)

0.72

0.64

1.3±0.05

2.25

0.15

0.7±0.05

STROKE CONDITION
SCALE 30:1

1.23
(SOLDER AREA)

1.05
(SOLDER AREA)

0.1

1

2

3

1.5

1.15

CONNECTOR
MOUNT AREA
PCB LAYOUT (REFERANCE)

△ FINISH (PLATING SPECIFICATION)
Ni UNDER PLATING : 0.0008mm TO 0.002mm
Au PLATING (CONTACT PLATING) : 0.00025mm TO 0.0005mm
AU PLATING (SOLDER PLATING) : 0.00005mm TO 0.0005mm

△ MATERIAL : COPPER ALLOY, THK.=0.1mm

△ CUTTING BURR : 0.05mm MAX.

4 DISUSED PACKAGEING MATERIAL : DRYPACK AND BAKING PROCESS

△ めっき仕様
Ni 下地めっき : 0.0008mm - 0.002mm
Au めっき (接点部めっき) : 0.00025mm TO 0.0005mm
AU めっき (半田部) : 0.00005mm TO 0.0005mm

△ 材料 : 銅合金, 板厚=0.1mm

△ カットバリ : 0.05mm以下

4 ドライバック及びベーキングは不要のこと

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION
IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
SHOULD BE CONTACTED FOR THE LATEST REVISION.

DWN Y.KUDO 01DEC2009

CHK C.OHASHI 01DEC2009

APVD Y.NAKAZAWA 01DEC2009

PRODUCT SPEC

108-78740

APPLICATION SPEC

WEIGHT 0.0044 g

 Tyco Electronics Corporation
Kawasaki, Japan

NAME SHIELD FINGER 1310

SIZE CAGE CODE DRAWING NO RESTRICTED TO

A300779 C=1554825

DIMENSIONS:
mmTOLERANCES UNLESS
OTHERWISE SPECIFIED:
±0.15

MATERIAL

FINISH

2

1

CUSTOMER DRAWING SCALE 20:1 SHEET 1 OF 2 REV A

1470-19 (2/09)

FJ044953

THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION

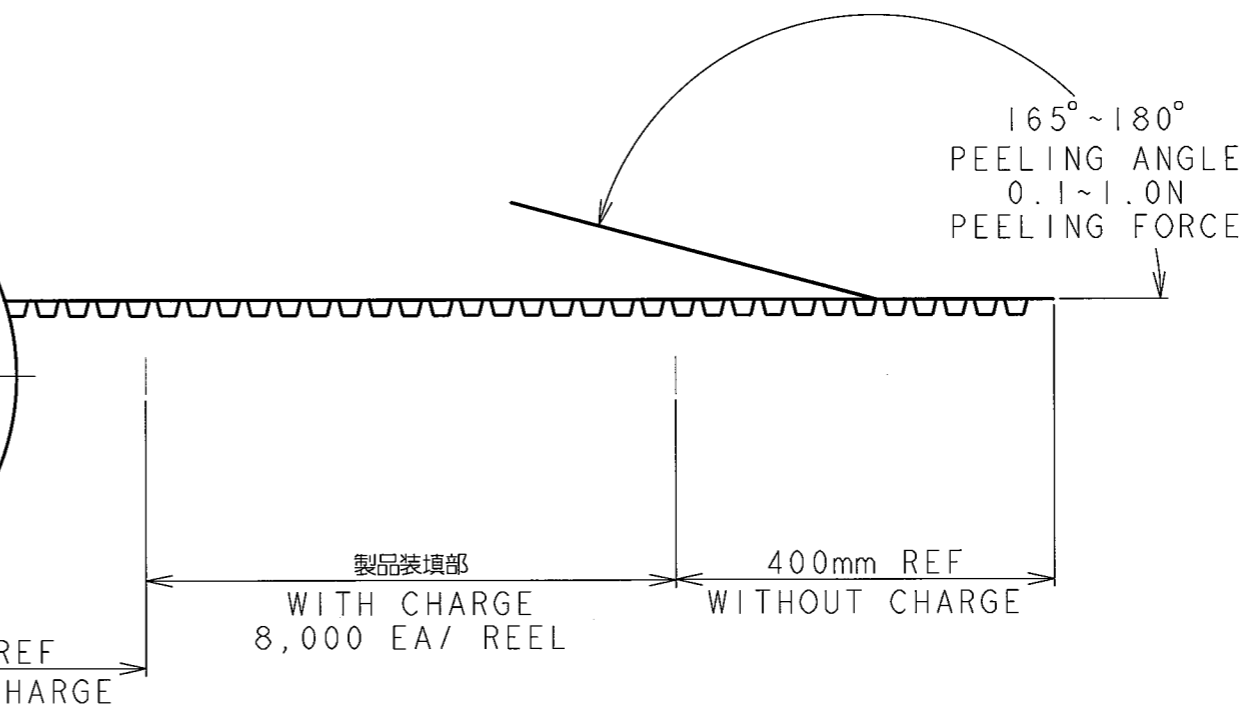
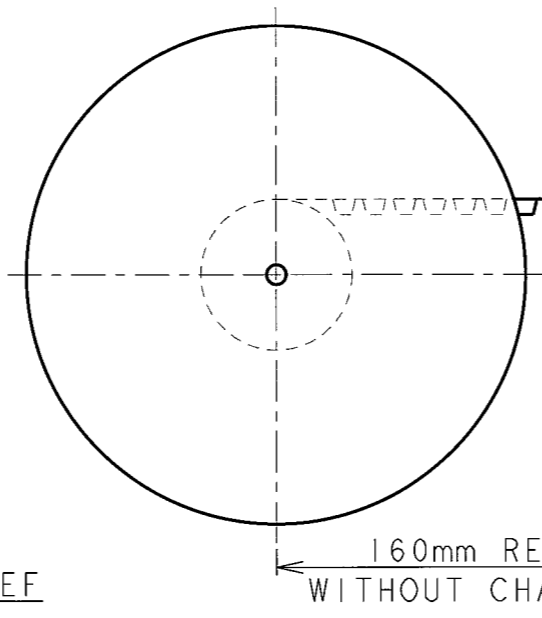
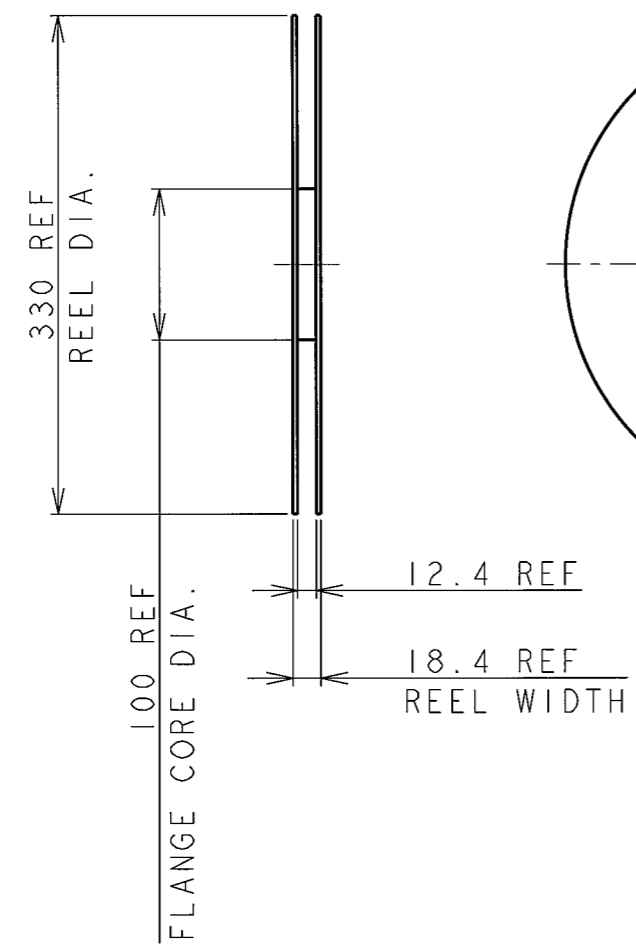
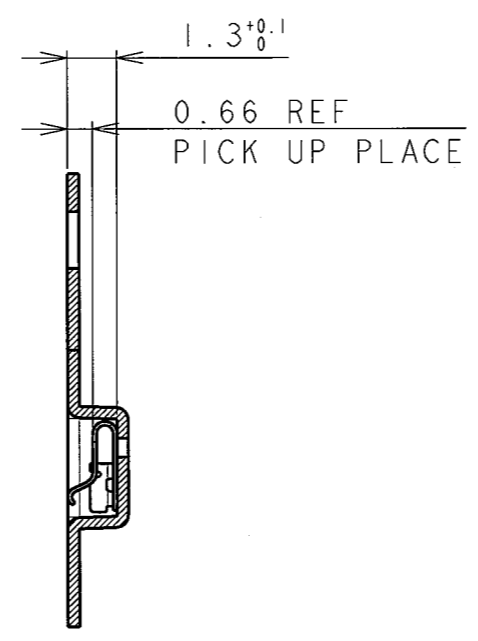
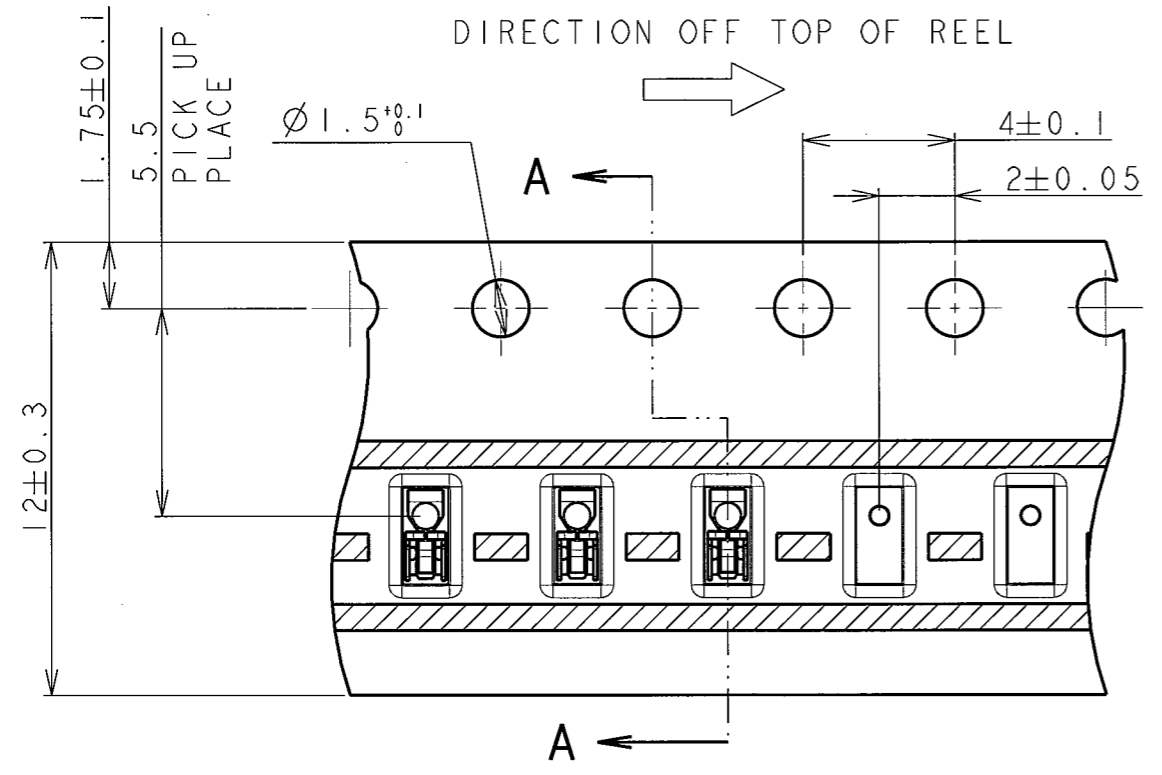
20

LOC DIST

REVISIONS

© COPYRIGHT 20 BY TYCO ELECTRONICS CORPORATION. ALL INTERNATIONAL RIGHTS RESERVED.

P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-



THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.2	DWN	Tyco Electronics Tyco Electronics Corporation Kawasaki, Japan
	0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±3°	CHK	
MATERIAL	FINISH	APVD	NAME
		PRODUCT SPEC	SHIELD FINGER 1310
		APPLICATION SPEC	SIZE CAGE CODE DRAWING NO RESTRICTED TO
		WEIGHT	A300779C-1554825
CUSTOMER DRAWING		SCALE 20:1	SHEET 2 OF 2 REV A